

Description

The HXY5P04MI uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

D G G SOT-23-3L

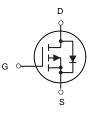
General Features

 $V_{DS} = -40V, I_{D} = -5A$

 $R_{DS(ON)} < 54m\Omega$ @ V_{GS} =10V

Application

High power and current handing capability
Lead free product is acquired
Surface mount package
PWM applications
Load switch
Power management



P-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
HXY5P04MI	SOT-23-3L	5P04	3000PCS

Absolute Maximum Ratings (T_A=25 ℃ unless otherwise noted)

Symbol	Parameter	Limit	Unit	
VDS	Drain-Source Voltage	-40	V	
V _G s	Gate-Source Voltage	±20	V	
I _D	Drain Current-Continuous	-5	А	
Ідм	Drain Current-Pulsed (Note 1)	-22	А	
P _D	Maximum Power Dissipation	2	W	
T _J ,T _{STG}	Operating Junction and Storage Temperature Range	-55 To 150	$^{\circ}$	
Reja	Thermal Resistance,Junction-to-Ambient (Note 2)	65	°C/W	

HXY5P04MI

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units	
Off Charac	Off Characteristic						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D = -250μA	-40	-	_	V	
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -40V, V _{GS} =0V	-	-	-1	μA	
I _{GSS}	Gate to Body Leakage Current	V _{DS} =0V, V _{GS} = ±20V	-	-	±100	nA	
On Characteristics							
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D = -250μA	-1.0	-1.6	-2.5	V	
Б	Static Drain-Source on-Resistance	V _{GS} = -10V, I _D = -5A	-	45	54	mΩ	
R _{DS(on)}	Note2	V _{GS} = -4.5V, I _D = -4A	-	60	85		
Dynamic (Characteristics						
C _{iss}	Input Capacitance	.,	-	869	-	pF	
Coss	Output Capacitance	V _{DS} = -20V, V _{GS} =0V, f=1.0MHz	-	94	_	pF	
C _{rss}	Reverse Transfer Capacitance	1-1.0IVIDZ	-	69	_	pF	
Qg	Total Gate Charge	\/ - 20\/ I - 4A	-	17.3	_	nC	
Q_{gs}	Gate-Source Charge	V_{DS} = -20V, I_{D} = -4A, V_{GS} = -10V	-	3.2	_	nC	
Q_{gd}	Gate-Drain("Miller") Charge	VGS10V	-	4.3	_	nC	
Switching	Switching Characteristics						
t _{d(on)}	Turn-on Delay Time		-	10.3	-	ns	
t _r	Turn-on Rise Time	V _{DS} = -20V, I _D = -4A,	-	4.3	-	ns	
t _{d(off)}	Turn-off Delay Time	V_{GS} = -10V, R_{GEN} =3 Ω	-	39	_	ns	
t _f	Turn-off Fall Time	all Time		46.5	_	ns	
Drain-Sou	Drain-Source Diode Characteristics and Maximum Ratings						
	Maximum Continuous Drain to Source	ce Diode Forward			5 0	Α	
I _S	Current		_		-5.0		
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-22	Α	
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} =0V, I _S = -5.5A	-	-0.8	-1.2	V	
trr	Reverse Recovery Time	V _{GS} =0V, I _S = -5.5A,	-	17	-	ns	
Qrr	Reverse Recovery Charge	di/dt=100A/µs	-	11.5	-	nC	

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

^{2.} Pulse Test: Pulse Width≤300 μ s, Duty Cycle≤2%



Typical Characteristics

Figure1: Output Characteristics

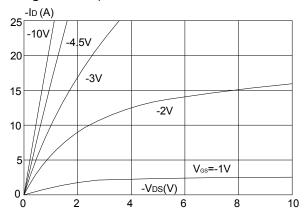


Figure 3:On-resistance vs. Drain Current

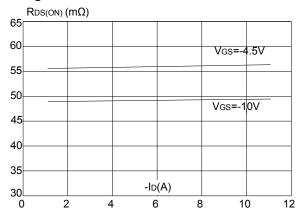


Figure 5: Gate Charge Characteristics

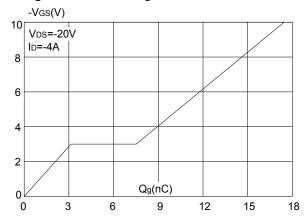


Figure 2: Typical Transfer Characteristics

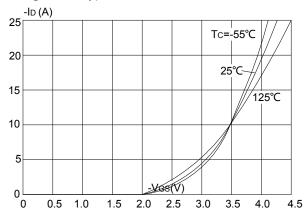


Figure 4: Body Diode Characteristics

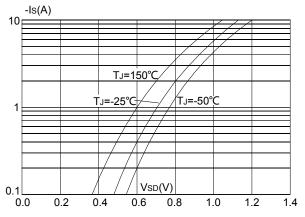


Figure 6: Capacitance Characteristics

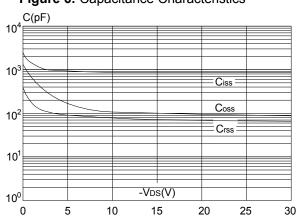




Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

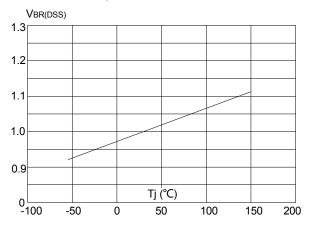


Figure 9: Maximum Safe Operating Area

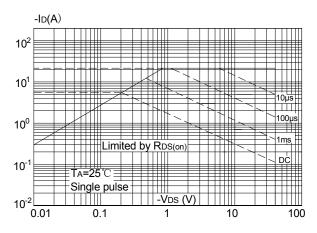


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

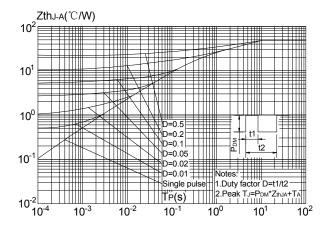


Figure 8: Normalized on Resistance vs. Junction Temperature

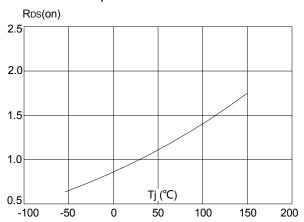
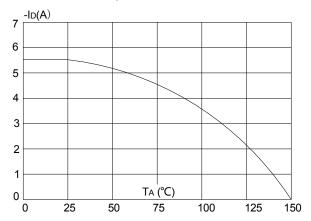
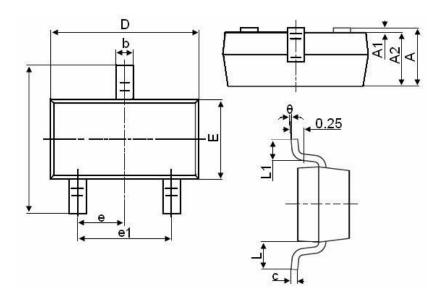


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature



HXY5P04MI

SOT-23-3L Package Information



Symbol	Dimensions in Millimeters		
	MIN.	MAX.	
Α	1.050	1.250	
A1	0.000	0.100	
A2	1.050	1.150	
b	0.300	0.500	
С	0.100	0.200	
D	2.800	3.000	
Е	1.500	1.700	
E1	2.650	2.950	
е	0.950TYP		
e1	1.800	2.000	
L	0.550REF		
L1	0.300	0.600	
θ	0°	8°	

HXY5P04MI P-Channel Enhancement Mode MOSFET

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